



08-28-2001



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RE

U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office
Docket No. 0819-0538

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Kenshi KANEGAE
Shinichi IMAI
Hideo NAKAGAWA

8-1501

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: 7/19/01

2. Name and address of receiving party(ies)

Name: Matsushita Electric Industrial Co., Ltd.

Internal Address: _____

Street Address: 1006, Oaza Kadoma

City: Kadoma-shi State: Osaka Zip: _____

Country: Japan Postal Code: 571-8501

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s);

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)
09/837,556

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Eric J. Robinson

Internal Address: Nixon Peabody LLP

Street Address: 8180 Greensboro Drive,

Suite 800

City: McLean State: VA Zip: 22102

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)\$ 40.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

19-2380

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Eric J. Robinson, Reg. No. 38,285

Name of Person Signing

Signature

August 15, 2001

Date

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

09/16/2001 CHINA/51 00000074 09037556

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NVA193226.1

PATENT
REEL: 012099 FRAME: 0441

ASSIGNMENT

WHEREAS, **Kenshi KANEGAE, Shinichi IMAI, Hideo NAKAGAWA**
(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements
in **ETCHING METHOD, SEMICONDUCTOR AND FABRICATING METHOD FOR THE**
SAME for which the undersigned has (have):

- (a) filed an application for Letters Patent of the United States of America on
April 19, 2001 having Serial No. 09/837,556; or
- (b) executed an application for Letters Patent of the United States of America on the date(s)
indicated below; and

WHEREAS, **Matsushita Electric Industrial Co., Ltd.** of
1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, Japan
its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is
desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters
Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in
hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the
undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer
unto the Assignee the full and exclusive right to the said invention in the United States of America and
its territories and for all foreign countries, dependencies and possessions and the entire right, title and
interest in and to the application and any and all Letters Patent(s) which may be granted therefor in the
United States of America and its territories, dependencies and possessions, and in and to any and all
divisions, reissues, continuations and extensions thereof for the full term or terms for which the same
may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application
and any continuing, divisional or reissue applications thereof and also to execute separate assignments
in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference
which may be declared concerning this application or any continuation, division or reissue thereof or
Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way
possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which
may be necessary in connection with claims under or provisions of the International Convention for the
Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to the Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

This Assignment has been executed by the undersigned on the date(s) indicated.

Date: July 19, 2001, Kenshi KANEGAE
Kenshi KANEGAE

Date: July 19, 2001, Shinichi Imai
Shinichi IMAI

Date: July 19, 2001, Hideo Nakagawa
Hideo NAKAGAWA

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____